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Innovativity To Productivity

PRODUCTIVE TECHNOLOGIES COMPANY LIMITED

普達特科技有限公司*

(Incorporated in Bermuda with limited liability)

(Stock Code: 650)

UPDATE ON DEVELOPMENT OF EQUIPMENT FOR SEMICONDUCTOR EQUIPMENT BUSINESS

This announcement is made by Productive Technologies Company Limited (the “**Company**”) on a voluntary basis to keep the shareholders and potential investors of the Company informed of the latest business development of the Company.

Reference is made to the announcement of the Company dated March 24, 2026 in relation to the development of the semiconductor equipment (the “**Announcement**”). Unless the context requires otherwise, the capitalized terms contained herein will have the same meanings as those defined in the Announcement.

ACQUISITION OF MULTIPLE FORMAL EQUIPMENT PURCHASE ORDERS

As the Company’s various semiconductor equipment platforms continue to achieve delivery and validation milestones at customer sites, the Company has accumulated substantial mass production experience and garnered widespread industry recognition, positioning the Company favorably to secure larger-scale formal orders. Since the date of the Announcement, the Company has successfully secured new orders for a total of 29 units of equipment, including new orders for 14 units of semiconductor equipment, encompassing single-wafer cleaning equipment and LPCVD furnace systems. These equipment systems are mainly used in customers’ high-end specialty process semiconductor and third-generation semiconductor production lines, covering both front-end and back-end wafer processing applications. The new orders are set out as below in descending order of the number of units:

1. OCTOPUS and OCTOPUS-SP single-wafer cleaning equipment, covering, among others, 12-inch wafer backside cleaning, Solvent cleaning, RCA cleaning processes, among which there are four units of sulfuric acid cleaning equipment;

* For identification purpose only

2. CUBE single-wafer cleaning equipment designed for backside cleaning and etching processes; and
3. LPCVD furnace equipment designed for 12-inch SiN thin film deposition processes.

The equipment orders referred to above are all formal orders, and revenue has not yet been recognized. The Company will recognize revenue upon completion of validation by the customers.

To the best of the Board's knowledge, information and belief, having made all reasonable enquiries, the customers mentioned above and their ultimate beneficial owners are third parties independent of the Company and its connected persons as at the date of this announcement.

The Company's independently developed semiconductor cleaning equipment and LPCVD/ALD furnace equipment platforms cater to both mature processes and advanced logic and memory processes, with technical performance benchmarked against leading international equipment manufacturers while offering industry-leading equipment productivity. The semiconductor cleaning equipment platforms, centered on the single-wafer cleaning systems, encompass mainstream wet cleaning applications such as solvent cleaning, wafer backside cleaning and RCA cleaning. Moreover, the Company has made further technological breakthroughs by developing and successfully shipping advanced high-temperature sulfuric acid cleaning equipment supporting high-temperature sulfuric acid cleaning processes up to 190°C. The Company's semiconductor furnace equipment platform comprises two advanced equipment lines, LPCVD and ALD, targeting critical thin film deposition processes for 12-inch wafers, including SiN, Poly and TEOS. Furthermore, the Company has completed the development of Low-K ALD SiOCN furnace tube equipment for high-performance dielectric layer thin film deposition at the 14/7nm nodes, a segment currently dominated by overseas equipment manufacturers.

Going forward, the Company is committed to fully leveraging its technological strengths, proactively expanding its market presence, securing additional batch formal orders and engaging more industry-leading customers, with the objective of driving the rapid growth of its semiconductor equipment business, enhancing gross profit margins and fostering the organic development of the Company.

GENERAL

The transactions contemplated under the abovementioned new orders do not constitute notifiable transactions of the Company under Chapter 14 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited. The Company will make further announcement(s) as and when appropriate if required.

Shareholders and potential investors are advised to exercise caution when dealing in the securities of the Company.

By Order of the Board
Productive Technologies Company Limited
Liu Erzhuang
Chairman and Chief Executive Officer

Hong Kong, October 11, 2026

As at the date hereof, the Board comprises eight Directors, of whom three are executive Directors, namely Dr. Liu Erzhuang (Chairman), Mr. Tan Jue and Mr. Liu Zhihai; two are non-executive Directors, namely Mr. Cao Xiaohui and Mr. Lin Yukai; and three are independent non-executive Directors, namely Ms. Ge Aiji, Mr. Chau Shing Yim David, and Mr. Wang Guoping.